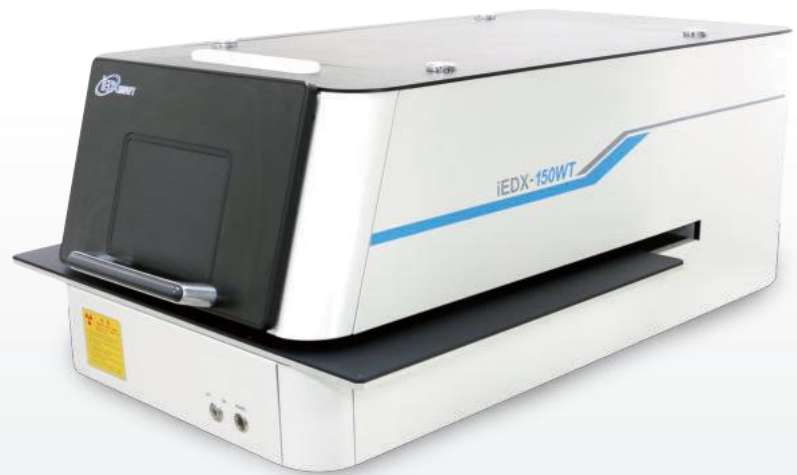




iEDX-150WT

Type : sp10, sp30, sp40, mp30, mp40
Coating Thickness Analyzer / Large scale PCB



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X-ray tube	• Mo/Rh/W/Ag Target(Optional), 50kVp, 1mA
Detection System	• Si-Pin Diode, (Option : Proportional Counter, SDD)
Energy Resolution	• Si-Pin Diode : 149eV FWHM at Mn K α Option < P C : 800eV FWHM at Mn K α SDD : 125eV FWHM at Mn K α
Collimator	• 0.3 Collimator (Option : 0.05, 0.1, 0.2, 0.5, 1mm) Manual / Auto Changing Stage
Detection Element	• Al(13) - U(92)
Sample Type	• Multi-Layer, Wide PCB
Size of the sample chamber	• 300mm X 282mm X 45mm (W x D x H) • Auto / Manual Stage Mode
Key Features	• Plating thickness measurement : General, Rh, Pd, Au, Ag, Sn, Ni • Film thickness measurement of multilayer thin films.(up to 5 Layer)
Camera Magnification	• 40~80 x
Safety	• 3 point interlock
Type of Report	• Excel, PDF / output • Custom form
Key Benefits	• Film thickness measurement of multilayer thin films, (up to 5 Layer) • Convenient stage control • Multi-point measurement possible • RoHS Screening(Optional) • Remote Support by Online
Application	• Product screening international environmental regulations (RoHS, WEEE, ELV compliant) • Hazardous material(Cr, Br, Cd, Hg, Pb, Cl, Sb, Sn, S) Screening equipment • Plating analysis automobile parts, Electronic circuit board (PCB), Such as a capacitor • Analysis of single-layer, Multi-layer, Alloy plating • Thickness with Composition Ratio can be measure on time in alloy plating



iEDX-1 50 μ T

High Performance Coating Thickness Analyzer

X-ray tube

- ◆ Mo/Rh/W/Ag Target(Optional), 50kVp, 1mA

Detection System

- ◆ SDD (Silicon Drift Detector)

Energy Resolution

- ◆ 125eV FWHM at Mn K α

Collimator

- ◆ Poly capillary optics (50~100 μ m)

Detection Element

- ◆ Al(13) - U(92)

Sample Type

- ◆ Solid / Liquid / Powder, Multi-Layer

Size of the sample chamber

- ◆ 390mm X 410mm X 100mm (W x D x H)

Key Features

- ◆ Auto / Manual Stage Mode
- ◆ Plating thickness measurement general, Rh, Pd, Au, Ag, Sn, Ni
- ◆ Film thickness measurement of multilayer thin films. (up to 5 Layer)

Camera Magnification

- ◆ 40~80 x

Safety

- ◆ 3 point interlock

Type of Report

- ◆ Excel, PDF / output
- ◆ Custom form

Key Benefits

- ◆ **Micro focused measuring point(<70 μ m) using capillary optics**
- ◆ Film thickness measurement of multilayer thin films. (up to 5 Layer)
- ◆ Convenient stage control
- ◆ Multi-point measurement possible
- ◆ Remote Support by on line

Application

- ◆ Plating thickness measurement special, ENEPIG, Pd-Ni, Rh etc.
- ◆ Plating analysis automobil parts, Electronic circuit board (PCB), Such as a capacitor
- ◆ Analysis of single-layer, Multi-layer, Alloy plating
- ◆ Thickness with Composition Ratio can be measure on time in alloy plating



Headquarter

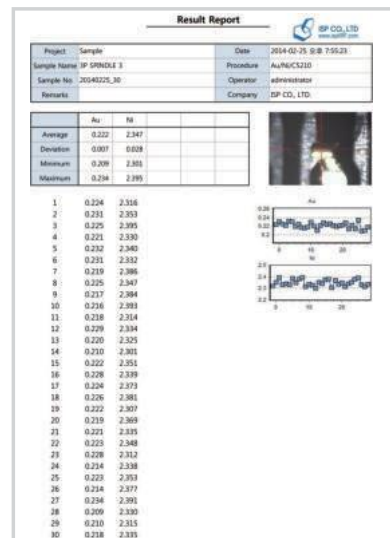
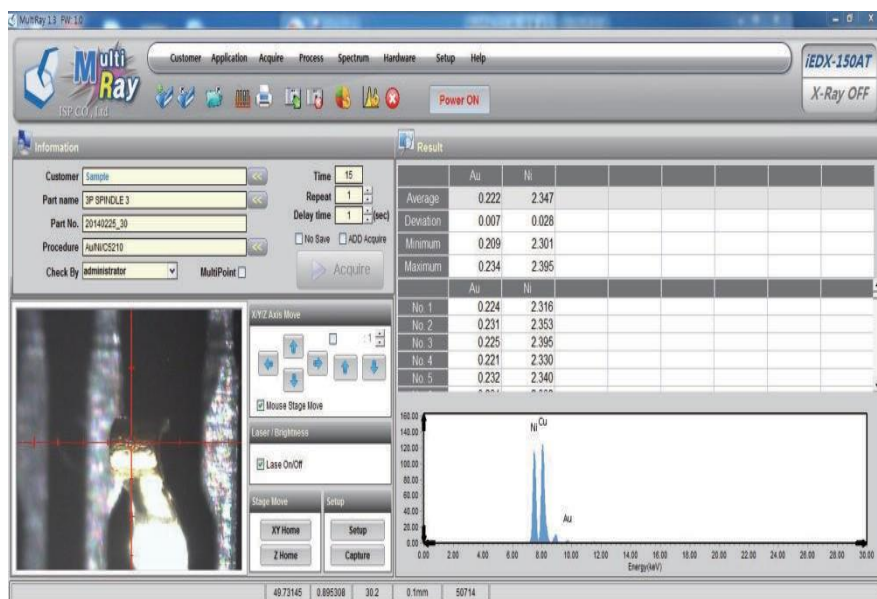
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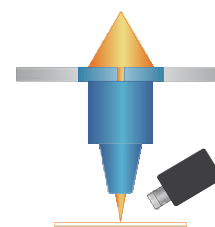
Coating Thickness Analysis Software

MultiRay



Report results of measurement plating thickness

- Multi-layer thickness analysis
- Simple plating layer define
- Convenient parameters setup
- Fundamental Parameters method, calibration curve method, absorption method support
- Define the concentration with elements on alloy layer
- PDF, EXCEL save function



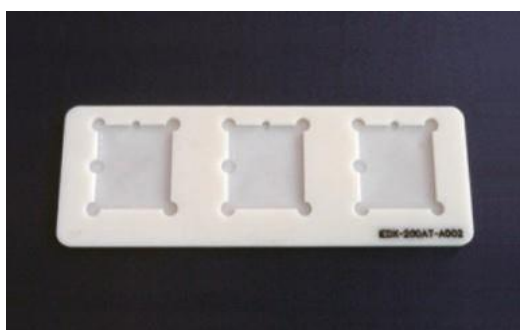
Capillary Optics Bundle
Typical Range : 50~100μm



〈Thickness Standard〉



〈Polycapillary & Monocapillary Optics〉



〈Coating thickness standard block〉



〈Coating thickness sample block〉





- Measure copper coating or plating thickness of the top layer on PCB by EN14571 standard with micro resistance method

iTG-B10

Copper Thickness Gauge

Measurement Method		4 Probe micro Resistance
Sample		Copper layer on PCB
Thickness Range	RANGE 1	0.1~10 μ m
	RANGE 2	10~120 μ m
Accuracy		$\pm$ 1% with reference to standards
Measuring Time		1 sec/point
Display Size		8 inch
Battery		Ion battery recharge
Memory capacity		Unlimited
Export of Results		Wireless printer, Excel, E-mail
Operating System		Android 4.4
Communication System		Bluetooth

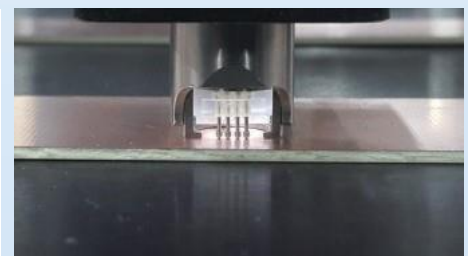
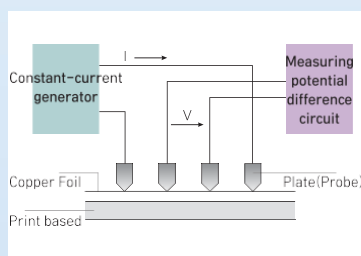


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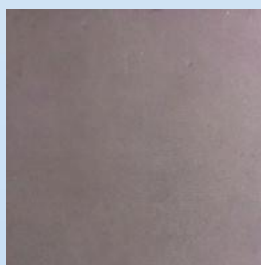
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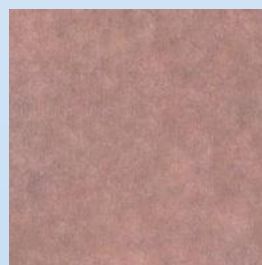


- 4 Probe micro resistance method is most effective way of accurate and precise measurement for copper layer on PCB

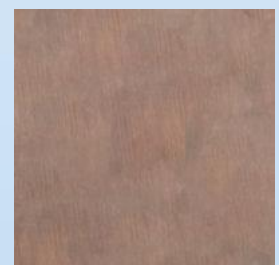
Standard Sample



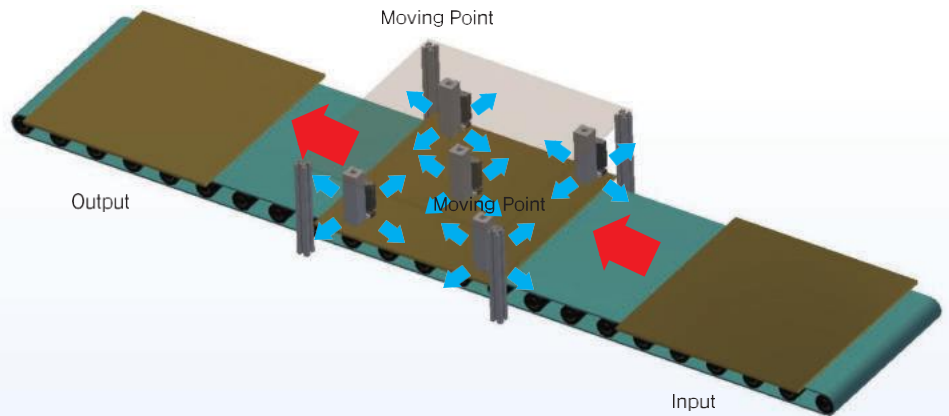
<5um Sample>



<11.5um Sample>



<31.7um Sample>



iTG-C10

In Line Copper Thickness Gauge

Measurement Method		4 Probe micro Resistance
Sample		Copper layer on PCB
Thickness Range	RANGE 1	0.1~10 μ m
	RANGE 2	10~120 μ m
Accuracy		$\pm$ 1% with reference to standards
Number of Measuring point		Up to 20 point
Report		Excel, PDF
Operating System		Window 7 or more
Interface		USB 2.0



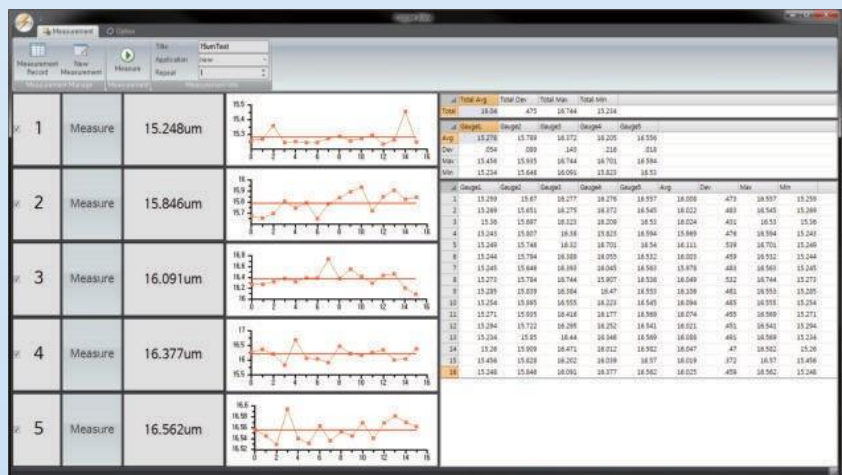
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User Interface



Reel to Reel

In-line Plating Thickness Gauge



X-ray tube

- Mo/Rh/W/Ag Target(Optional), 50kVp, 1mA

Detection System

- SDD (Silicon Drift Detector)
- P.C(Proportional Counter)

Collimator

- Poly capillary optics

Detection Element

- Al(13) - U(92)

Key Features

- Auto / Manual Stage Mode
- Plating thickness measurement general, Rh, Pd, Au, Ag, Sn, Ni
- Film thickness measurement of multilayer thin films. (up to 5 Layer)

Camera Magnification

- 40~80 x

Type of Report

- Excel, PDF / output
- Custom form

Application

- Plating thickness measurement special, ENEPIG, Pd-Ni, Rh etc.
- Plating analysis automobil parts, Electronic circuit board (PCB), Such as a capacitor
- Analysis of single-layer, Multi-layer, Alloy plating
- Thickness with Composition Ratio can be measure on time in alloy plating

Headquarter

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iEDX-750T

Plating Thickness Analyzer



Headquarter

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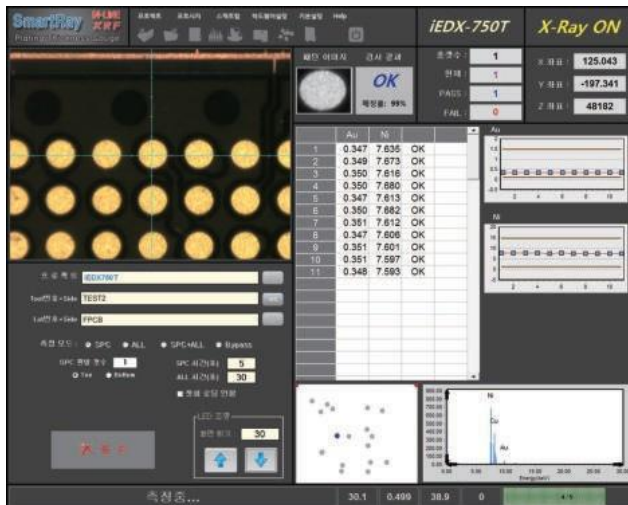
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X-ray tube	♦ Mo/Rh/W/Ag Target(option), 50kVp, 1mA
Detection System	♦ SDD(Silicon Drift Detector)
Energy Resolution	♦ 125eV FWHM at Mn K α
Collimator	♦ Poly Capillary Optics(FWHM 15~30 μ m)
Detection Element	♦ Al(13)~U(92)
Sample Type	♦ Wide PCB
Sample Size	♦ Max : 510 x 415
Equipment Size	♦ 2600mm x 1350mm x 2050mm(W x D x H)
Utility	♦ Power : Single-Phase 220V, 4kw ♦ Air Pressure : 5kgf
Key Features	♦ Plating thickness measurement general, Rh, Pd, Au, Ag, Sn, Ni ♦ Film thickness measurement of multilayer thin films.(up to 5 Layer)
Camera Magnification	♦ 40~80 Magnification
Safety device of Radioactivity	♦ Cut-off device for an automatic 3
Type of Report	♦ Excel, PDF / output ♦ Custom form
Key Benefits	♦ Film thickness measurement of multilayer thin films, (up to 5 Layer) ♦ Convenient stage control ♦ Multi-point measurement possible
Application	♦ ENIG, ENEPIG ♦ Electronic circuit board (PCB) ♦ The analysis of the exact content when measuring plating thickness

Plating Thickness Program

iEDX-750T

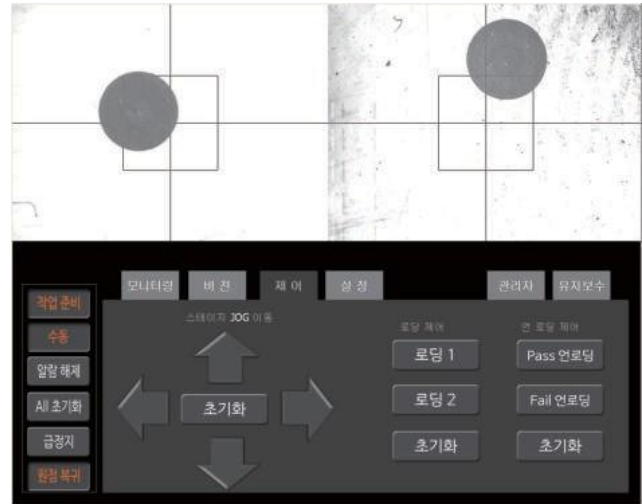
Main UI



> Function

- ◆ Multipoint automatic measurement
- ◆ Sample Pattern Matching Test
- ◆ Display Result Pass/Fail
- ◆ Display Spectrum

Align UI



> Function

- ◆ Automatic / manual control
- ◆ Alarm Reset
- ◆ initialization
- ◆ Emergency stop and home return
- ◆ Align status Monitoring
- ◆ Stage control

Option

Cartridge type Loader & Unloader

